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# News Fact Sheet

## INTEL PRE-CES BRIEFING SUMMARY

**Dec. 14, 2007** – Intel Corporation held briefings on Dec. 14 in New York and San Francisco to provide an update on the latest trends and technologies in mobile, ultra mobile, desktop computing and consumer electronics. A summary of the topics discussed and new disclosures are included below.



### **Mobility: Intel Announces Santa Rosa Refresh Product Line**

***Santa Rosa Refresh*** – In January, Intel will launch “Santa Rosa Refresh,” an update to Intel® Centrino® processor technology that includes the next-generation 45 nanometer (nm) high-k (Hi-k) mobile processor (codenamed “Penryn”) and improved graphics capabilities.

- ***45nm Hi-k Intel® Core™2 Duo mobile processor for Centrino*** – Taking advantage of the Hafnium-based, Hi-k metal gate reinvented transistors inside, Santa Rosa Refresh-based notebooks deliver improved platform performance and great battery life. Graphics improvement focuses on HD DVD and Blu-Ray support with an optional third-party decoder, as well as enhanced content and gaming capabilities.
- ***Santa Rosa Refresh for Desktop*** -- Intel will also use this new mobile technology foundation with the energy-efficient performance of the 45nm Intel Core 2 Duo processor to enable a variety of smaller, cooler and quieter, stylish desktop designs.



### **Ultra Mobility: Full Internet in Your Pocket**

Intel’s strategy for delivering full Internet “in your pocket” is based on using low-power Intel Architecture (IA) platforms that drastically reduce CPU and chipset power and package size for a range of ultra mobile and mobile Internet devices. Intel can achieve these lower power products thanks to its combination of reinvented transistors, 45nm manufacturing and microarchitecture design features.

- ***Intel Confirms “Menlow” Platform Shipments in the first half of 2008*** – Intel is getting ready to ship its first-generation low-power platform, codenamed “Menlow,” in the first half of 2008. The Menlow platform is comprised of the “Silverthorne” processor and the “Poulsbo” chipset, both being designed from the ground up for Mobile Internet Devices (MID) and Ultra Mobile PCs (UMPCs). At CES, Intel is planning to provide a sneak peek of the some of the “Menlow”-based devices and applications that are being optimized for this platform.
- ***Intel Unveils Customers and Ecosystem Players Planning to Showcase Menlow-based Platforms at CES:*** In a sign of growing ecosystem momentum behind MIDs and UMPCs, Intel

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plans to showcase a range of customers and ecosystem players who are working with the company to launch Menlow-based platforms and applications at CES. Expect Intel to demonstrate a range of Menlow-based MIDs and UMPCs from Aigo\*, Asus\*, BenQ\*, Clarion\*, Compal\*, Elektrotbit\*, Inventec\*, Lenovo\*, Quanta\* and others in the booth.



### **Flash: Intel Introduces Smallest Solid-State Drive in Hot NAND Market**

As consumers seek to store more multimedia in the form of songs, photos and Internet pages in their portable devices, the drive for faster, smaller and more rugged forms of memory has driven the growth of NAND flash applications.

- **Intel Synonymous with Solid-State Drives** – Intel’s Flash Memory NAND Products Group (NPG) announced its latest foray into the solid-state drive (SSD) market in its quest to make Intel synonymous with SSD technology.
- **Intel Introduces Intel® Z-P140 PATA SSD – the Smallest SSD in the Industry** – Intel introduced the Intel Z-P140 PATA Solid-State Drive, the tiniest SSD in the industry aimed at small and ultra-small form factors. Smaller than a penny and the weight of a drop of water, these 2 Gigabyte (GB) and 4GB ultra small devices (extendable to 16GB) are fast, low-power and rugged, with the right size, right capacity and right performance for mobile Internet devices, digital entertainment and embedded products. The Intel Z-P140 PATA SSD has an industry-standard parallel-ATA (PATA) interface. Optimized to enhance Intel Architecture platforms, the Intel Z-P140 PATA SSD is also part of Intel’s proposed Menlow platform (<http://developer.intel.com/go/NAND/>).



### **WiMAX: Mobile WiMAX Takes the Stage in 2008**

Mobile WiMAX, based on the IEEE 802.16e industry specification, is a broadband wireless technology that provides low-cost, multi-megabit speed and great throughput for accessing large amounts of data such as movies and multi-media content.

- **Global mobile WiMAX adoption continues to grow** – Intel continues to work with Sprint and Clearwire on the deployment of a mobile WiMAX network in the United States starting in 2008. Intel is also working with carriers around the world to deploy mobile WiMAX networks globally.
  - Comstar and Intel recently announced a joint collaboration to build a citywide mobile WiMAX network in Moscow using Comstar’s 2.5-2.7GHz spectrum footprint. The commercial launch of Comstar’s mobile WiMAX network is targeted for late 2008.
- **Intel WiMAX Silicon Plans** – Intel’s integrated Wi-Fi/WiMAX module will be available as an option with next-generation Intel Centrino processor technology for laptops (codenamed “Montevina”) next year. The company’s mobile WiMAX silicon specifically designed for mobile Internet and consumer electronic devices will also be available in early 2008.



### **Consumer Desktop PCs: 45nm Goes Mainstream**

- **“Penryn” Family of Processors Come to Desktop PCs** – In the first quarter of 2008, Intel will extend the performance and energy efficiency of its 45nm Hafnium-based Hi-k metal gate transistor-based “Penryn” family of processors to consumer desktop PCs. These new Intel® Core™ 2 Quad and Intel Core 2 Duo processors (formerly codenamed “Yorkfield” and “Wolfdale,” respectively) will bring mainstream desktop computing performance to new levels. These processors will ship at a range of speeds and bring Intel’s energy-efficient 45nm Hi-k Hafnium-based processors to mainstream systems. These processors will feature enhancements

such as larger L2 caches and Intel® HD Boost, which helps to boost performance for certain video, photo and high-performance computing software applications.

- **Intel® Core™2 Processor with Viiv™ Technology** – In the first quarter of 2008, Intel will extend the performance and energy efficiency of its new 45nm processors with Intel HD Boost to this platform. The hardware included with Intel Core 2 Processor with Viiv Technology-based PCs provides not only outstanding performance for computing tasks but a great digital media experience by enabling 1080P high-definition video playback and up to 7.1 surround sound audio. Intel will also focus its future plans on delivering silicon-driven capabilities that support the areas of better connecting, protecting and managing digital content – as well as delivering the performance required to view, share and enjoy it.
- **In the first quarter of 2008, Intel will continue its progression of leading-edge technology products:**
  - **The Intel® Core™ 2 Extreme QX9770 Processor** (3.2 GHz/1600 MHz system bus 45nm Hi-k metal gate processor formerly codenamed “Yorkfield”) and Intel® X48 Express Chipset targeted at high-end PC users and enthusiasts. The Intel X48 Express Chipset continues to push the performance envelope with native support for XMP 1600 DDR3 memory.
  - **“Skulltrail”** is a new dual processor-based platform that will provide extreme high-end enthusiasts with a fantastic professional media creation and gaming experience. The platform will feature dual quad-core Intel Core 2 Extreme processors for 8-core performance and 4 PCI Express x16 Gen 1.1 slots with planned support for up to 4 graphics cards.



**Consumer Electronics: Intel in CE**

- **Intel in Consumer Electronics** – Intel will deliver system-on-a-chip (SoC) products for a new generation of Internet compatible consumer electronics (CE) devices, such as set top boxes, digital media recorders and digital TVs. In April, Intel unveiled the CE 2110 Media Processor, a complete SoC architecture that combines a 1GHz processing core with powerful A/V processing and graphics, and I/O components onto a single chip.
- **Intel's first CE-optimized IA-based SoC, codenamed “Canmore”** – Scheduled for 2008, it will pair a powerful IA processor with leading-edge A/V processing, graphics and more to help deliver greater performing Internet-compatible devices. By incorporating many features and standards into Intel’s silicon products, these SoCs will help manufacturers accelerate product delivery and deliver more cost-effective designs that provide strong processing performance and flexibility.

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